*AMENDMENTS TO THE CLAIMS*

This listing of claims replaces all prior versions, and listings, of claims in the application.

Claim 1 (Cancelled).

2. (Currently Amended) The multi-layer ~~printed~~ wiring board of claim ~~1~~ 6, wherein

~~the~~said pair of first ~~portion is generally~~ portions are arcuate, and

~~the~~said pair of second ~~portion is positioned within a virtual arcuate extension of of the first portion~~ portions are linear.

3. (Currently Amended) The multi-layer ~~printed~~ wiring board of claim ~~1~~ 2, wherein

~~the one of the through-hole and the~~said ground through-hole closest to the center of said land is positioned along a line generally perpendicular to said signal line and passing through the center of said land, and

~~a portion of the~~one of said second ~~portion and having a minimum radius of the external periphery is positioned on~~ portions intersects the line generally perpendicular to said signal line.

4. (Currently Amended) The multi-layer ~~printed~~ wiring board of claim ~~1~~ 6, ~~including a plurality of~~ wherein said ground through-holes are positioned along lines lying on opposite sides of said signal line.

5. (Withdrawn-Currently Amended) The multi-layer ~~printed~~ wiring board of claim ~~1~~ 6, ~~including~~ wherein a plurality of ~~the~~ said ground through-holes are equidistant from the center of said ~~land~~ signal through-hole and ~~lying~~ lie along a plurality of ~~directions~~ lines passing through the center of said ~~land~~ signal through-hole, ~~wherein~~ and at least one of the ~~external periphery of said land has a second portion lying along and intersecting each of the directions and a first portion between each pair of second portions~~ lines passing through the center of said signal through-hole is coincident with the second diameter .

6. (New) A multi-layer wiring board comprising:

a plurality of electrically conducting layers laminated in a stack, with electrical insulation intervening between each closest pair of electrically conducting layers, said electrically conducting layers including

a power supply layer,

at least two signal layers, and

a plurality of ground layers, alternating layers in said stack being ground layers;

a plurality of electrically conducting ground through-holes having respective centers, penetrating through said stack, and electrically connecting said ground layers to each other; and

an electrically conducting signal through hole penetrating through said stack and electrically connecting said signal layers together, wherein

at least one of said signal layers includes a land surrounding and electrically connected to said signal through-hole, and a signal line extending from and electrically connected to said land,

said land includes a pair of first portions extending outwardly from opposite sides of said signal through-hole, said pair of first portions defining a first width of said land lying along a first diameter of said signal through-hole, the diameter passing through a center of said signal through-hole,

said land includes a pair of second portions extending outwardly from opposite sides of said signal through-hole, said pair of second portions defining a second width of said land lying along a second diameter of said signal through-hole, and

the first and second diameters are not co-linear, the second width is shorter than the first width, and the second diameter lies on a line connecting the center of said signal through-hole and the center of said ground through-hole closest to said signal through-hole.

7. (New) The multi-layer wiring board of claim 6, wherein said pair of first portions and said pair of second portions are arcuate.

8. (New) The multi-layer wiring board of claim 7 including a plurality of pairs of said first portions and of said second portions.

9. (New) The multi-layer wiring board of claim 5 wherein the second diameter is oblique to said signal line.

10. (New) The multi-layer wiring board of claim 5 wherein the second diameter is generally perpendicular to said signal line.